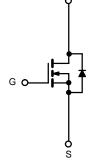


## AUIRFU8405-VB Datasheet N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a, c</sup>	Q <sub>g</sub> (Typ.)			
40	0.0016 at V <sub>GS</sub> = 10 V	120	120 nC			
	0.0020 at V <sub>GS</sub> = 4.5 V	100	120110			
	D					
	•					



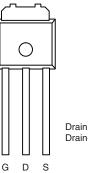
#### FEATURES

- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

#### **APPLICATIONS**

- Synchronous Rectification
- Power Supplies





TO-251

Top View

Drain Connected to Drain-Tab

N-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage	VI	semive6688	40	V
Gate-Source Voltage		V <sub>GS</sub>	± 25	v
	T <sub>C</sub> = 25 °C		120 <sup>a, c</sup>	
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 70 °C		96 <sup>c</sup>	
Continuous Drain Current $(T_j = TTS^{-1}C)$	T <sub>A</sub> = 25 °C		29 <sup>b</sup>	A
	T <sub>A</sub> = 70 °C		23 <sup>b</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	250	1	
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	96	
Single Pulse Avalanche Energy	L = 0.1 mm	E <sub>AS</sub>	320	mJ
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	- I <sub>S</sub>	120 <sup>a, c</sup>	Α
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	'S	2.6 <sup>b</sup>	A
	T <sub>C</sub> = 25 °C		312 <sup>a</sup>	
Movimum Dowor Dissinction	T <sub>C</sub> = 70 °C	P <sub>D</sub>	200	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	FD FD	3.13 <sup>b</sup>	VV
	T <sub>A</sub> = 70 °C	1	2.0 <sup>b</sup>	
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.33	0.4	C/W	

Notes:

a. Based on T<sub>C</sub> = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 120 A.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V$ , $I_{D} = 250 \mu A$	40			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		41		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 8			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.2		2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 V, V_{GS} = 0 V$			1	μA	
Zero Gale voltage Drain Current		$V_{DS} = 40$ V, $V_{GS} = 0$ V, $T_{J} = 55$ °C			10 <sup>µ</sup>		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	120			А	
Drain Source On State Resistenced	Base	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$		0.0016			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0020		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		180		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			9000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, f = 1 MHz		650			
Reverse Transfer Capacitance	C <sub>rss</sub>			450			
Total Gate Charge	Qg			120	180	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 20 V, $V_{GS}$ = 10 V, $I_{D}$ = 20 A		30			
Gate-Drain Charge	Q <sub>gd</sub>			16			
Gate Resistance	Rg	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			20	30		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 20 V, $R_L$ = 1.0 $\Omega$		11	17	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_{\text{D}}\cong$ 20 A, $\text{V}_{\text{GEN}}$ = 10 V, $\text{R}_{g}$ = 1 $\Omega$		77	115		
Fall Time	t <sub>f</sub>			10	15		
Turn-On Delay Time	t <sub>d(on)</sub>			102	155	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, \text{ R}_{1} = 1.0 \Omega$		62	95		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		180	270		
Fall Time	t <sub>f</sub>			60	90	1	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			110	•	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				200	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C		50	75	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			70	105	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			30			
Reverse Recovery Rise Time	t <sub>b</sub>			20		ns	

Notes:

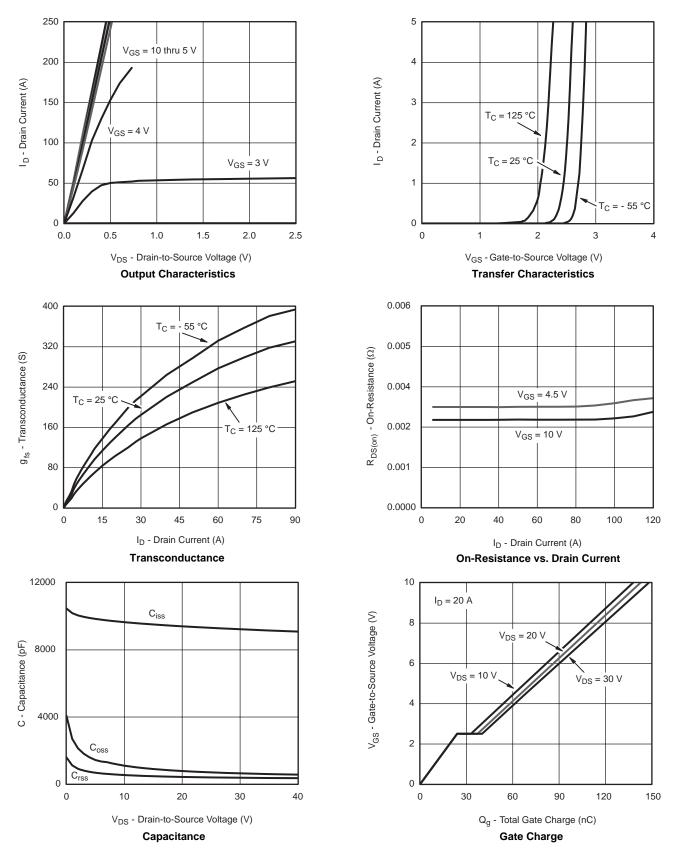
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

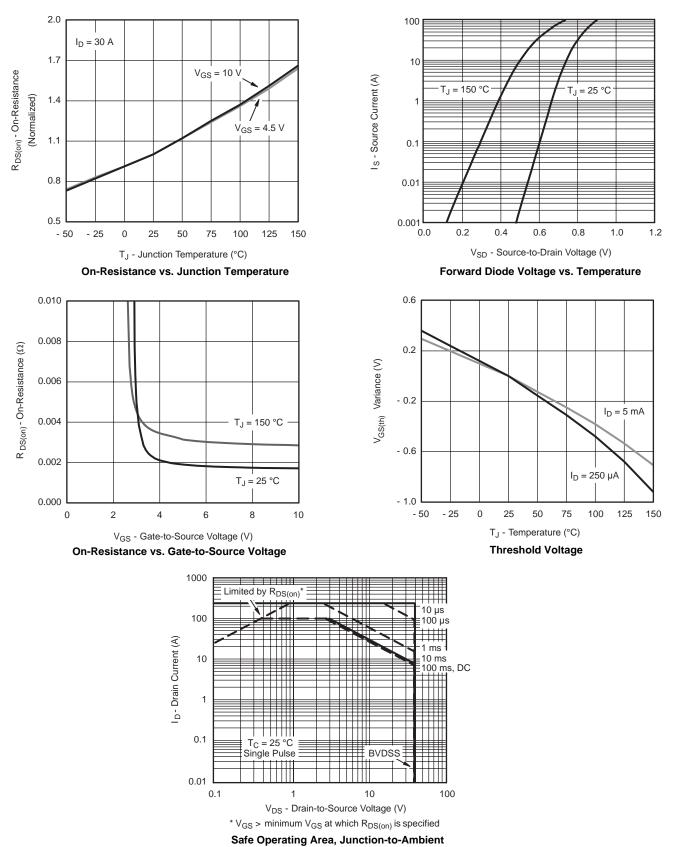


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

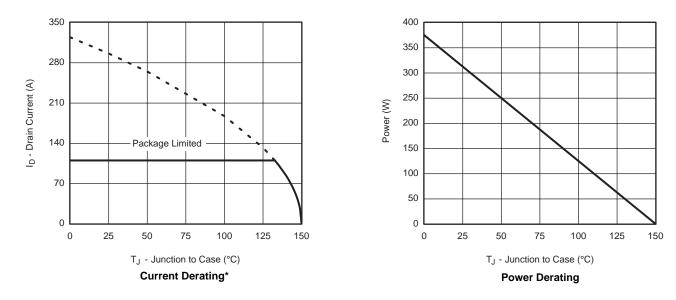




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

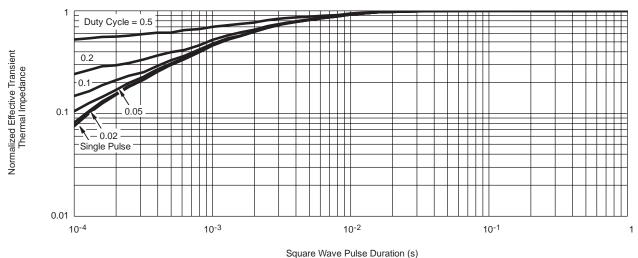






#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

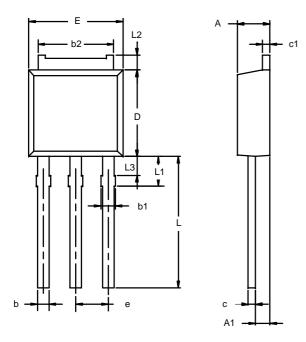


Normalized Thermal Transient Impedance, Junction-to-Case

## AUIRFU8405-VB



#### **TO-251AA**



	MILLIMETERS IN			HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
Е	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060

Note: Dimension L3 is for reference only.



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